

LED SPECIFICATION

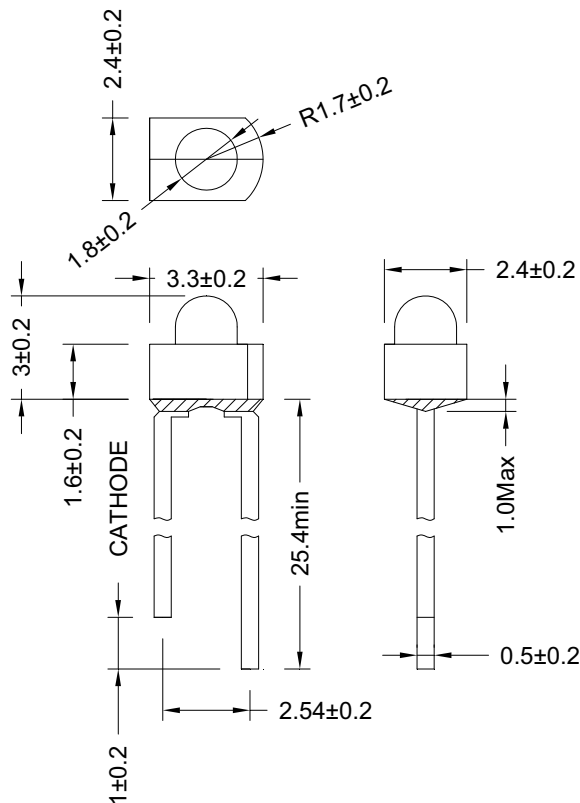
Part No.: 130PG2C

➤ **Features/特征:**

- Single color/单色
- High bright output/高亮度输出 t
- Low power consumption/低功率
- High reliability and long life/
可靠性高、寿命长

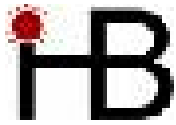
➤ **Descriptions/描述:**

- Dice material/芯片材质: InGaN
- Emitting Color/发光颜色:
Super Bright Blue Green/ 高亮度绿色
- Device Outline/产品外形:
Special Type/ 特殊形状
- Lens Type 胶体颜色:
Water Clear/ 无色透明



NOTE:

- All dimensions are millimeters/单位: mm..
- Tolerance is ± 0.25 mm unless otherwise noted/
没有标注的公差均为 ± 0.25 mm



LED SPECIFICATION

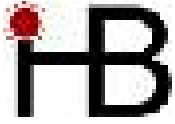
Part No.: 130PG2C

Absolute maximum ratings/极限参数 (Ta = 25°C)

| Parameter 参数 | Symbol 符号 | Test Condition 测试条件 | Values 数值 | | Unit 单位 |
|---------------------------------|-------------------|-------------------------|-----------|------|------------|
| | | | Min. | Max. | |
| Reverse Voltage 反向电压 | V _R | I _R = 30 μ A | 5 | -- | V |
| Forward Current 正向工作电流 | I _F | ---- | ---- | 30 | mA |
| Power Dissipation 损耗功率 | P _d | ---- | ---- | 80 | mW |
| Pulse Current 正向峰值电流 | I _{peak} | Duty=0.1mS, 1kHz | ---- | 100 | mA |
| Operating Temperature 工作温度范围 | T _{opr} | ---- | -40 | +85 | °C |
| Storage Temperature 储存温度范围 | T _{str} | ---- | -40 | +100 | °C |

➤ Electrical and optical characteristics/光电参数 (Ta = 25°C)

| Parameter 参数 | Symbol 符号 | Test Condition 测试条件 | Values 数值 | | | Unit 单位 |
|-----------------------------------|----------------|------------------------|-----------|------|------|------------|
| | | | Min. | Typ. | Max. | |
| Forward Voltage 正向电压 | V _F | I _F = 20mA | ---- | 3.2 | 3.6 | V |
| Reverse Current 反向电流 | I _R | V _R = 5V | ---- | ---- | 30 | μ A |
| Dominate Wavelength 主波长 | λ _d | I _F = 20mA | ---- | 525 | ---- | nm |
| Peak Wavelength 峰值波长 | λ _p | I _F = 20mA | ---- | 520 | ---- | nm |
| Spectral Line half-width 半波长宽度 | Δ λ | I _F = 20mA | ---- | 25 | ---- | nm |
| Luminous Intensity 发光强度 | I _v | I _F = 20mA | ---- | 1500 | ---- | mcd |



LED SPECIFICATION

Part No.: 130PG2C

➤ **Typical electrical/optical characteristic curves/光电特性曲线:**

Fig.1 正向电流 Vs. 正向电压

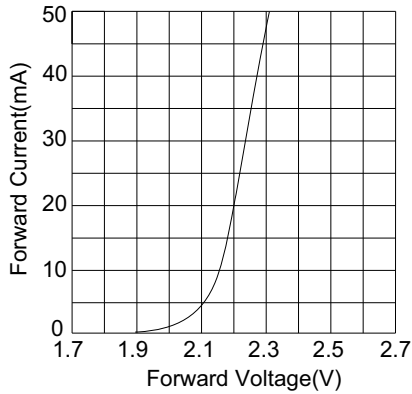


Fig.2 相对亮度 Vs. 正向电流

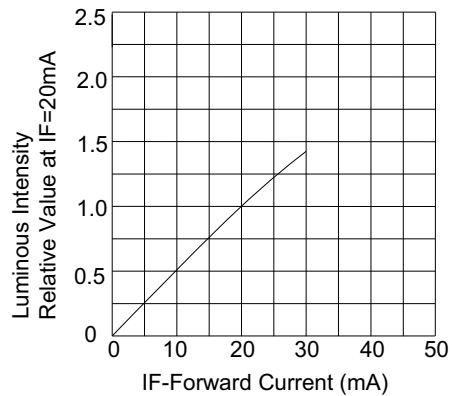


Fig.3 正向电流 Vs. 环境温度

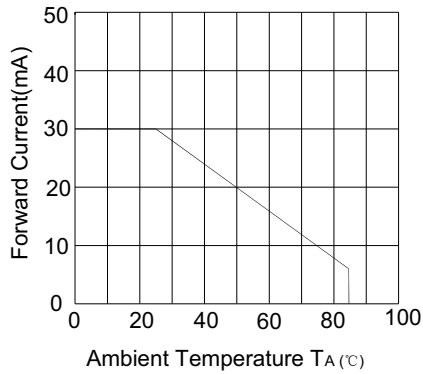


Fig.4 相对亮度 Vs. 环境温度

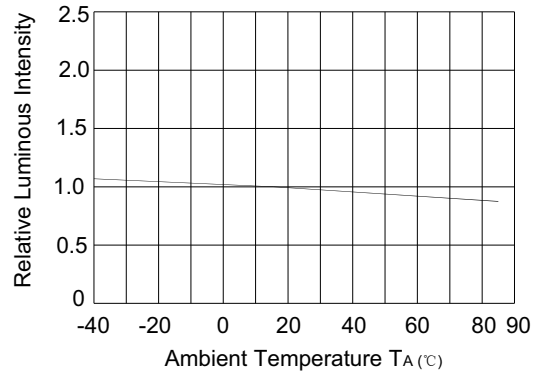
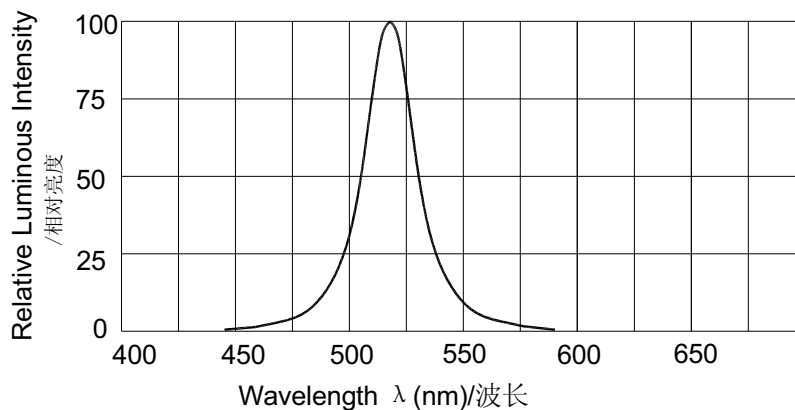


Fig.5 辐射强度 Vs. 波长





BIN ranking for LEDs

BRIGHTNESS BIN

| Bin Code | IV(mcd) | Bin Code | IV(mcd) | Bin Code | IV(mcd) | Bin Code | IV(mcd) |
|----------|-----------|----------|-----------|----------|-----------|----------|------------|
| A | 0-5.0 | H | 37.2-52.0 | Q | 390-550 | X | 4180--5860 |
| B | 5.0-7.0 | J | 52.0-72.8 | R | 550-770 | Y | 5860-8200 |
| C | 7.0-9.8 | K | 72.8-102 | S | 770-1100 | Z1 | 8-10cd |
| D | 9.8-13.7 | L | 102-145 | T | 1100-1520 | Z2 | 10-12cd |
| E | 13.7-19.0 | M | 145-200 | U | 1520-2130 | Z3 | 12-14cd |
| F | 19.0-26.6 | N | 200-280 | V | 2130-3000 | Z4 | 14-16cd |
| G | 26.6-37.2 | P | 280-390 | W | 3000-4180 | Z5 | 16-18cd |

WAVELENGTH BIN

| Ligth Col. | Bin Code | Wavel. (nm) | Ligth Col. | Bin Code | Wavel. (nm) | |
|-------------------|-------------------|-------------|---------------------|----------------------|-------------|---------|
| BLUE | B1 | 450-455 | YELLOW GREEN | YG1 | 555-558 | |
| | B2 | 455-460 | | YG2 | 558-561 | |
| | B3 | 460-465 | | YG3 | 561-564 | |
| | B4 | 465-470 | | YG4 | 564-567 | |
| | B5 | 470-475 | | YG5 | 567-570 | |
| | B6 | 475-480 | | YG6 | 570-573 | |
| BLUE GREEN | G1 | 491-494 | | YG7 | 573-576 | |
| | G2 | 494-497 | YELLOW | Y1 | 582-585 | |
| | G3 | 497-500 | | Y2 | 585-588 | |
| | G4 | 500-503 | | Y3 | 588-591 | |
| | G5 | 503-506 | | Y4 | 591-594 | |
| | G6 | 506-509 | | Y5 | 594-597 | |
| | PURE GREEN | G7 | 509-512 | YELLOW ORANGE | YO1 | 597-600 |
| | | G8 | 512-515 | | YO2 | 600-603 |
| G9 | | 515-518 | PURE ORANGE | YO3 | 603-606 | |
| G10 | | 518-521 | | YO4 | 606-609 | |
| G11 | | 521-524 | | RED | O1 | 609-612 |
| G12 | | 524-527 | O2 | | 612-615 | |
| G13 | | 527-530 | O3 | | 615-618 | |
| G14 | | 530-533 | R1 | | 618-621 | |
| G15 | | 533-536 | R2 | | 621-624 | |
| G16 | | 536-539 | R3 | | 624-627 | |
| G17 | | 539-542 | R4 | 627-630 | | |
| G18 | | 542-545 | R5 | 630-633 | | |
| G19 | | 545-548 | R6 | 633-636 | | |

FORWARD VOLTAGE (VF) BIN

| Bin Code | VF (V) | Bin Code | VF (V) | Bin Code | VF (V) | Bin Code | VF (V) |
|----------|---------|----------|---------|----------|---------|----------|---------|
| V1 | 1.6-1.8 | V5 | 2.4-2.6 | V9 | 3.2-3.4 | V13 | 4.0-4.2 |
| V2 | 1.8-2.0 | V6 | 2.6-2.8 | V10 | 3.4-3.6 | V14 | 4.2-4.4 |
| V3 | 2.0-2.2 | V7 | 2.8-3.0 | V11 | 3.6-3.8 | V15 | 4.4-4.6 |
| V4 | 2.2-2.4 | V8 | 3.0-3.2 | V12 | 3.8-4.0 | V16 | 4.6-4.8 |

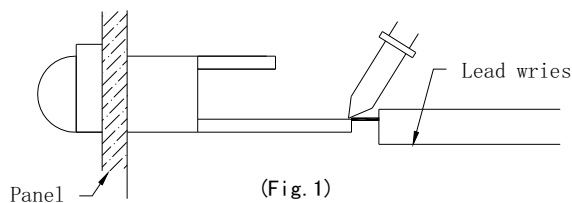


LED LAMP APPLICATION

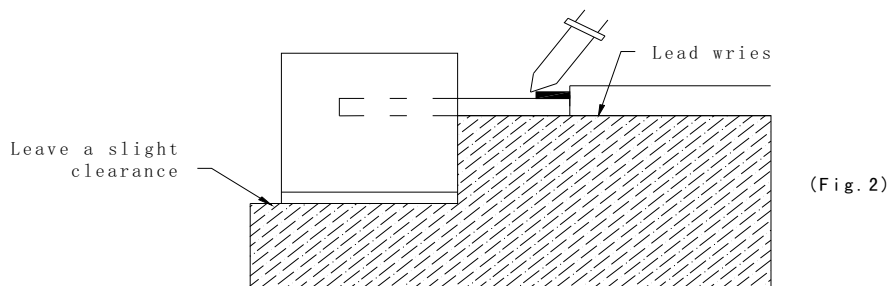
•SOLDERING

| METHOD | SOLDERING CONDITIONS | REMARK |
|----------------|---|--|
| DIP SOLDERING | Bath temperature: $260\pm 5^{\circ}\text{C}$ Immersion time: with 5 sec | <ul style="list-style-type: none">• Solder no closer than 3mm from the base of the package• Using soldering flux, "RESIN FLUX" is recommended. |
| SOLDERING IRON | Soldering iron: 30W or smaller Temperature at tip of iron: 260°C or lower Soldering time: within 5 sec. | <ul style="list-style-type: none">• During soldering, take care not to press the tip of iron against the lead. (To prevent heat from being transferred directly to the lead, hold the lead with a pair of tweezers while soldering |

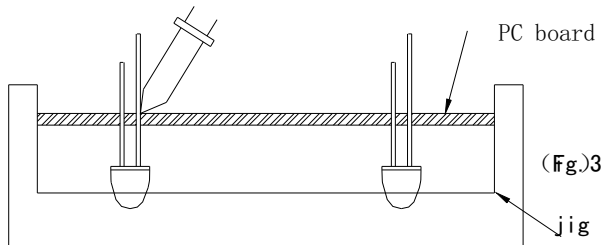
- 1) When soldering the lead of LED in a condition that the package is fixed with a panel (See Fig.1), be careful not to stress the leads with iron tip.



- 2) When soldering wire to the lead, work with a Fig (See Fig.2) to avoid stressing the package.



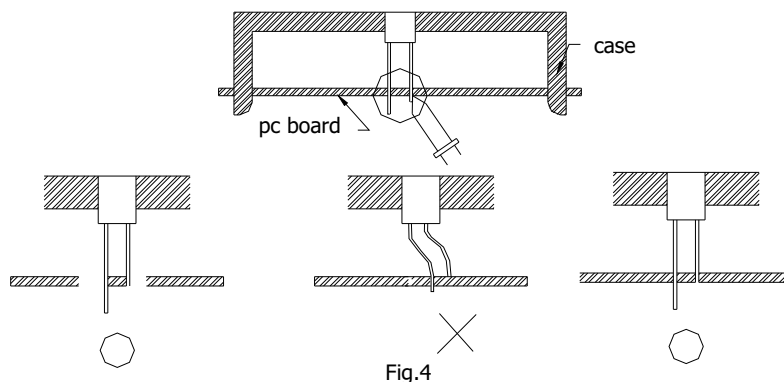
- 3) Similarly, when a jig is used to solder the LED to PC board, take care as much as possible to avoid steering the leads (See Fig.3).



- 4) Repositioning after soldering should be avoided as much as possible. If inevitable, be sure to preserve the soldering conditions with irons stated above: select a best-suited method that assures the least stress to the LED.
- 5) Lead cutting after soldering should be performed only after the LED temperature has returned to normal temperature.

•LED MOUNTING METHOD

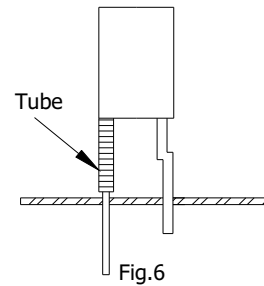
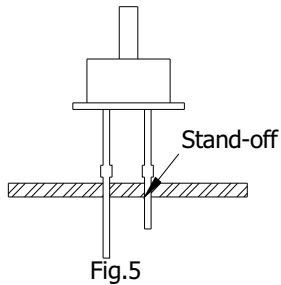
- 1) When mounting the LED by using a case, as shown Fig.4, ensure that the mounting holds on the PC board match the pitch of the leads correctly-tolerance of dimensions of the respective components including the LED should be taken into account especially when designing the case, PC board, etc. to prevent pitch misalignment between the leads and board holes, the diameter of the board holes should be slightly larger than the size of the lead. Alternatively, the shape of the holes should be made oval. (See Fig.4)





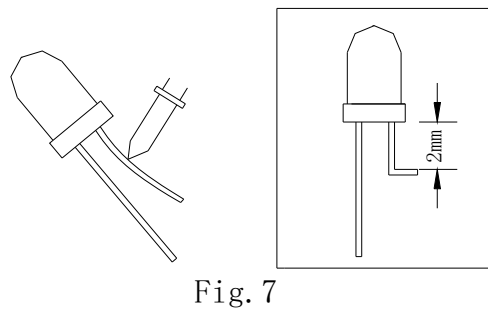
LED LAMP APPLICATION

2) Use LEDs with stand-off (Fig.5) or the tube or spacer made of resin (Fig.6) to position the LEDs.

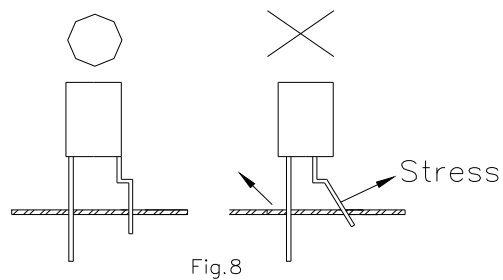


•FORMED LEAD

1) The lead should be bent at a point located at least 2mm away from the package. Bending should be performed with base fixed means of a jig or pliers (Fig.7)



2) Forming lead should be carried out prior to soldering and never during or after soldering.
3) Form the lead to ensure alignment between the leads and the hole on board, so that stress against the LED is prevented. (Fig.8)





•LEAD STRENGTH

1) Bend strength

Do not bend the lead more than twice. (Fig.9)

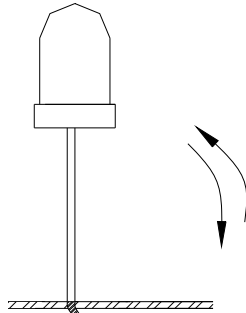


Fig.9

2) Tensile strength (@Room Temperature)

If the force is 1kg or less, there will be no problem. (Fig.10)

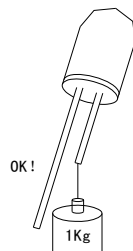


Fig.10

•HANDLING PRECAUTIONS

Although rigid against vibration, the LEDs may damaged or scratched if dropped. So take care when handling.

•CHEMICAL RESISTANCE

1) Avoid exposure to chemicals as it may attack the LED surface and cause discoloration.

2) When washing is required, refer to the following table for the proper chemical to be sued.

(Immersion time: within 3 minutes at room temperature.)

| SOLVENT | ADAPTABILITY |
|-------------------|--------------|
| Freon TE | ⊙ |
| Chlorothene | × |
| Isopropyl Alcohol | ⊙ |
| Thinner | × |
| Acetone | × |
| Trichloroethylene | × |

⊙--Usable ×--Do not use.

NOTE: Influences of ultrasonic cleaning of the LED resin body differ depending on such factors as the oscillator output, size of the PC board and the way in which the LED is mounted.

Therefore, ultrasonic cleaning should only be performed after confirming there is no problem by conducting a test under practical.

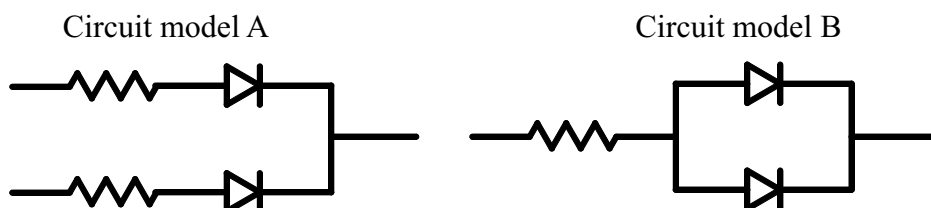


LED LAMP PASSED TESTS

Experiment Item:

| Item | Test Condition | Reference Standard |
|--|---|--|
| | Lamp & IR | |
| OPERATION LIFE | $T_a : 25 \pm 5^\circ\text{C}$ $I_F = 20\text{mA}$ RH : $\leq 60\%RH$ ① DYNAMIC: 100mA 1ms $1/10$ duty ② STATIC STATE: $I_F = 20\text{mA}$ TEST TIME: 168HRS (-24HRS , $+24\text{HRS}$) 500HRS (-24HRS , $+24\text{HRS}$) 1000HRS (-24HRS , $+72\text{HRS}$) | MIL-STD-750 : 1026 MIL-STD-883 : 1005 JIS C 7021 : B-1 |
| HIGH TEMPERATURE HIGH HUMIDITY STORAGE | $T_a : 65^\circ\text{C} \pm 5^\circ\text{C}$ RH : $90 \sim 95\%RH$ TEST TIME : $240\text{HRS} \pm 2\text{HRS}$ | MIL-STD-202 : 103B JIS C 7021 : B-1 |
| TEMPERATURE CYCLING | $105^\circ\text{C} \sim 25^\circ\text{C} \sim -55^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min 10CYCLES | MIL-STD-202 : 107D MIL-STD-750 : 1051 MIL-STD-883 : 1010 JIS C 7021 : A-4 |
| THERMAL SHOCK | $105^\circ\text{C} \pm 5^\circ\text{C} \sim -55^\circ\text{C} \pm 5^\circ\text{C}$ 10min 10min 10CYCLES | MIL-STD-202 : 107D MIL-STD-750 : 1051 MIL-SYD-883 : 1011 |
| SOLDER RESISTANCE | $T, \text{sol} : 260^\circ\text{C} \pm 5^\circ\text{C}$ DWELL TIME : $10 \pm 1\text{sec}$ | MIL-STD-202 : 210A MIL-STD-750-2031 JIS C 7021 : A-1 |
| SOLDERABILITY | $T, \text{sol} : 230^\circ\text{C} \pm 5^\circ\text{C}$ DWELL TIME : $5 \pm 1\text{sec}$ | MIL-STD-202 : 208D MIL-STD-750 : 2026 MIL-STD-883 : 2003 JIS C 7021 : A-2 |

Drive Method



(A) Recommended circuit.

(B) The difference of brightness between LED's could be found due to the V_f - I_f characteristics of LED.